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ILNAS-EN IEC 62878-2-5:2019

Device embedding assembly technology - Part 2-5: Guidelines - Implementation of a 3D data format for device embedded substrate

Montageverfahren für eingebettete
Bauteile - Teil 2-5: Leitfaden -
Implementierung eines 3D-Datenformats
für Trägermaterial mit eingebetteten

Techniques d'assemblage avec
intégration d'appareils - Partie 2-5 :
Lignes directrices - Mise en œuvre d'un
format de données 3D pour un substrat

11/2019



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**Device embedding assembly technology - Part 2-5: Guidelines -
Implementation of a 3D data format for device embedded
substrate
(IEC 62878-2-5:2019)**

Techniques d'assemblage avec intégration d'appareils -
Partie 2-5 : Lignes directrices - Mise en œuvre d'un format
de données 3D pour un substrat avec appareils intégrés
(IEC 62878-2-5:2019)

Montageverfahren für eingebettete Bauteile - Teil 2-5:
Implementierung eines 3D-Datenformats für Trägermaterial
mit eingebetteten Bauteilen
(IEC 62878-2-5:2019)

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European foreword

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Part 2-5: Guidelines – Implementation of a 3D data format for device embedded
substrate**

CONTENTS

FOREWORD	5
1 Scope	7
2 Normative references	7
3 Terms and definitions	7
4 Data definition	10
4.1 Flow chart design of device embedded substrate	10
4.2 Applicable range	11
4.2.1 Product	11
4.2.2 Process	12
4.3 Features	13
4.3.1 General	13
4.3.2 Device embedded substrate structure	13
4.3.3 SiP interposer structure	14
4.3.4 Virtual layer description	15
4.3.5 Terminal structure and embedded device structure including an SiP	15
4.3.6 Total design data of an SiP and device embedded substrate	15
4.4 Data description summary	16
4.4.1 Type of data and structures	16
4.4.2 File structure	18
4.5 3D expression	19
4.5.1 General	19
4.5.2 Coordinates	19
4.5.3 Position description	20
4.5.4 Relation between coordinate origin and board position	20
4.6 Layer concept	21
4.7 Substrate data	21
4.7.1 General	21
4.7.2 Layer map information	22
4.7.3 Device arrangement information	23
4.7.4 Basic figures	25
4.7.5 Net information	31
4.7.6 Artwork information	32
4.7.7 Package information	32
4.7.8 External port information	33
4.7.9 Internal port information	33
4.7.10 User expansion information	33
4.8 Defined data	33
4.8.1 General	33
4.8.2 Layer definition	33
4.8.3 Land definition	34
4.8.4 Via definition	35
4.8.5 Device definition	36
4.8.6 User expansion definition	37
5 Data organization and data description based on XML schema	38
5.1 General	38
5.2 Data organization of Example 1	38
5.3 Data description of layer stack-up	39

5.4	Data description of device	43
5.5	Data organization of layer	47
5.6	Data description of via	50
5.7	Data description of land	51
	Bibliography	53

Figure 1	– Flow chart of design of device embedded substrate	11
Figure 2	– General structure of device embedded substrate	12
Figure 3	– Example of device embedded substrate structure	14
Figure 4	– Examples of SiPs	14
Figure 5	– Example of virtual layer description	15
Figure 6	– Terminal structure	15
Figure 7	– Structure of SiP on a device embedded substrate	16
Figure 8	– Data structure	18
Figure 9	– One file structure (recommended)	19
Figure 10	– Two file structure	19
Figure 11	– Definition of coordinates	20
Figure 12	– Position definition	20
Figure 13	– Relation between coordinates and board position	21
Figure 14	– Layer concept	21
Figure 15	– Layer construction	22
Figure 16	– Simplified layer construction	23
Figure 17	– Layer definition of pad connection	24
Figure 18	– Layer definition of via connection	24
Figure 19	– Rotation direction on <i>X</i> , <i>Y</i> , and <i>Z</i> axes	25
Figure 20	– Point	26
Figure 21	– Area	27
Figure 22	– Lines	27
Figure 23	– Letters	28
Figure 24	– Letter shape	28
Figure 25	– Bonding wire information	29
Figure 26	– Semi-sphere	29
Figure 27	– Truncated pyramid	30
Figure 28	– Via	30
Figure 29	– Device definition	31
Figure 30	– Group	31
Figure 31	– Data structure of net information	32
Figure 32	– Relation of layer definition data	34
Figure 33	– Land definition	35
Figure 34	– Relation between hole information and land information	36
Figure 35	– Device with internal connection information	37
Figure 36	– Device without internal connection information	37
Figure 37	– Cross sectional view of Example 1	38
Figure 38	– Data organization of Example 1	38

Figure 39 – Data description of Example 1	39
Figure 40 – Layer structure of Example 1	40
Figure 41 – Data description of layer stack-up	42
Figure 42 – Configuration of device 1	43
Figure 43 – Data description of device 1	44
Figure 44 – Configuration of device 2	45
Figure 45 – Data description of device 2	46
Figure 46 – Layer view of Example 1	48
Figure 47 – Data description of layers	50
Figure 48 – Type of vias	51
Figure 49 – Data description of vias	51
Figure 50 – Type of lands	52
Figure 51 – Data description of lands	52
 Table 1 – Required information	 13
Table 2 – List of data	17